

ASSIGNMENT OF PATENT APPLICATION

(Inventors) **Chiuming LEUNG**
Kosuke TANAKA
Kazuki SATO
Cheukwing LEUNG
Juren DING
Rongkwang Ni
Wanyin KWAN
Mankit LEE

In consideration of the sum of one dollar (\$1.00) and other good and valuable considerations paid to each of the undersigned, the undersigned agree(s) to assign, and hereby does assign, transfer and set over to

(Assignee) **SAE Magnetics (H.K.) Ltd. and TDK Corporation**
(Address) of SAE Technology Centre, 6 Science Park East Avenue, Hong Kong Science Park, Shatin, N.T., Hong Kong, China; and TDK Kabushiki Kaisha, No. 13-1, 1-Chome, Nhonbashi, Chuo-ku, Tokyo, Japan

(Other Countries) (hereinafter designated as the Assignee) the undersigned's entire right, title and interest for the United States, its territories, dependencies and possessions, and for the country of in the invention, and all application(s) for patent and any Letters Patent which may be granted therefor, known as

(Title) **MAGNETORESISTIVE SENSOR, MAGNETIC HEAD, HEAD GIMBAL ASSEMBLY, AND DISK DRIVE UNIT WITH THE SAME (Case No.4593-306)**

for which the undersigned has (have) executed on even date herewith an application for patent in the United States of America or, if not on even date, then has executed on or has already filed in

U.S. appln. Serial No. 12/801,518, filed on June 11,2010

The undersigned acknowledges an obligation of assignment of this invention to said assignee at the time the invention was made.

The undersigned agree(s) to execute all papers and documents necessary in connection with the application or any interference which may be declared and any continuing or divisional applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient and further to perform any act which may be necessary in connection with claims or provisions of the International Convention for Protection of Industrial Property or similar agreements.


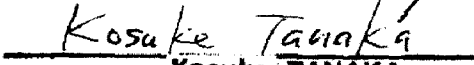
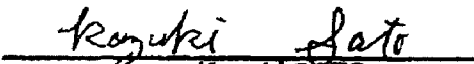

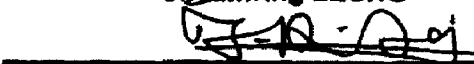


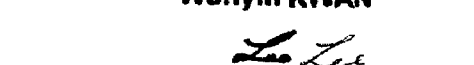
The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent to the Assignee.

The undersigned hereby authorize(s) and request(s) the Commissioner of Patents to issue any and all Letters Patent of the United States resulting from said application or any division or divisions or continuing applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) full right to convey the entire interest herein assigned, and that he has (they have) not executed and will not execute, any agreement in conflict herewith.

The undersigned hereby grant(s) the firm of NIXON & VANDERHYE P.C. the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent Office for recordation of this document. It is understood and agreed that ASSIGNEE'S attorneys Nixon & Vanderhye P.C. have represented only ASSIGNEE and will continue to represent only ASSIGNEE with respect to this invention.

In witness whereof, executed by the undersigned on the date(s) opposite the undersigned signature(s).

In witness whereof, executed by the undersigned on the date(s) opposite the undersigned signature(s).

Date <u>6/25/2010</u>	Signature of Inventor	 Chiuming LEUNG
Date <u>7/7/2010</u>	Signature of Inventor	 Kosuke TANAKA
Date <u>6/30/2010</u>	Signature of Inventor	 Kazuki SATO
Date <u>6/25/2010</u>	Signature of Inventor	 Cheukwing LEUNG
Date <u>6/23/2010</u>	Signature of Inventor	 Juren DING
Date <u>6/22/2010</u>	Signature of Inventor	 Rongkwang NI
Date <u>6/25/2010</u>	Signature of Inventor	 Wanyin KWAN
Date <u>6/25/2010</u>	Signature of Inventor	 Mankit LEE